



Product Change Notification

Change Notification #: 117063 - 00
Change Title: Intel® Spare Drive Bays & Carrier Options
FXX35HSCAR2,
PCN 117063-00, Product Design,
3.5" Tool-Less Carrier Design Improvement
for 2.5" Drive Support
Date of Publication: July 12, 2019

Key Characteristics of the Change:
Product Design

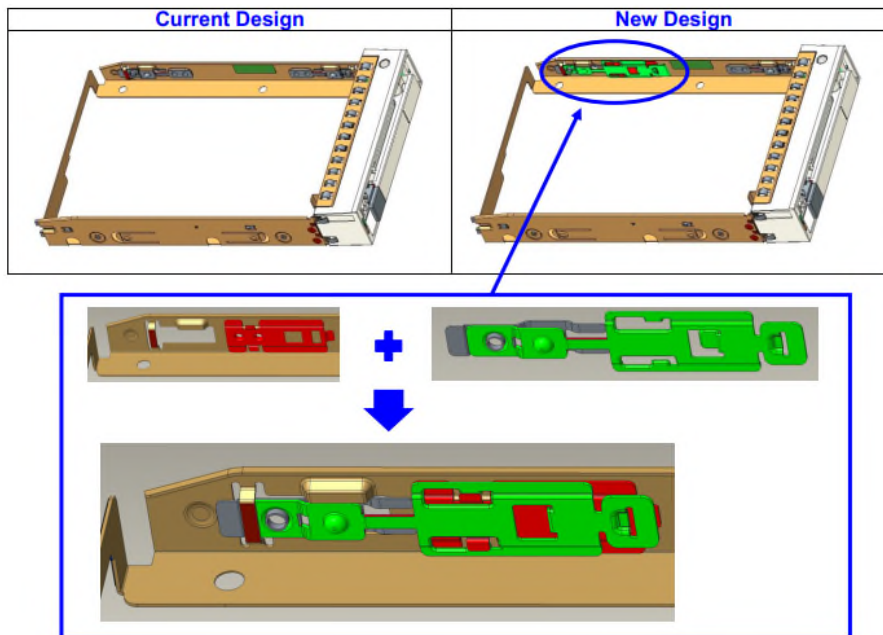
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	July 29, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing an improvement on FXX35HSCAR2 3.5" tool-less drive carrier for 2.5" drive support, new rear spring (see image in green) and new spring holder (see image in red) attached to the tool-less drive carrier. Removing the rear spring of 3.5" tool-less carrier when Install 2.5" SSD drive, installing the rear spring to support 3.5" HDD.



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
FXX35HSCAR2	958245	J37328-002	J37328-003

PCN Revision History:

Date of Revision:

July 12, 2019

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apagccb@intel.com

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